



Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F051R4T6 STM32F051R4T6TR	S25W*440XXX1	A	998Z	27-07-2017
	Amount	UoM	Unit type	ST ECOPACK Grade
	357.39	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10X1.4	64	L Bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	S25W*440XXX1			6000000.0	0.0	
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.974	mg	supplier	die	Silicon (Si)	7440-21-3		6.689	mg	959134	18716
				supplier	metallization	Aluminium (Al)	7429-90-5		0.019	mg	2724	53
				supplier	metallization	Copper (Cu)	7440-50-8		0.097	mg	13909	271
				supplier	metallization	Cobalt (Co)	7440-48-4		0.018	mg	2581	50
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	717	14
				supplier	metallization	Tungsten (W)	7440-33-7		0.011	mg	1577	31
				supplier	Passivation	Silicon Nitride	12033-89-5		0.013	mg	1864	36
				supplier	Passivation	Silicon Oxide	7631-86-9		0.122	mg	17494	341
Die Attach Epoxy_ABLEBOND 3230_H	M-011 Other inorganic materials	2.381	mg	Supplier	Metals	Silver	7440-22-4		2.145	mg	901000	6002
				Supplier	Plastics/polymers	Highly cross-linked polymer	Proprietary		0.236	mg	99000	660
Mold Compound_EME-G631SHQ_Sur	M-011 Other inorganic materials	248.711	mg	Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		5.002	mg	21000	13995
				Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		5.002	mg	21000	13995
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		13.338	mg	56000	37321
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		196.417	mg	780450	450413
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		27.467	mg	115320	76855
Wire_AG SI TYPE_MKE	Bonding Wire	0.389	mg	Supplier	Non-metals	Carbon Black	1333-86-4		1.484	mg	6230	4152
				Supplier	Metals	Silver	7440-22-4		0.373	mg	960000	1044
Plating anode_Pure Tin_Nuo Nengda	M-011 Other inorganic materials	1.438	mg	Supplier	Metals	Others	Proprietary		0.016	mg	40000	44
				Supplier	Metals	Tin	7440-31-5		1.438	mg	1000000	4023
Leadframe_C9+Ag_HDS	Copper & its alloys	97.500	mg	Supplier	Metals	Iron	7439-89-6		2.132	mg	21865	5965
				Supplier	Non-metals	Phosphorus	7723-14-0		0.071	mg	730	199
				Supplier	Metals	Zinc	7440-66-6		0.110	mg	1125	307
				Supplier	Metals	Copper	7440-50-8		89.040	mg	913235	249139
				Supplier	Metals	Silver	7440-22-4		6.143	mg	63000	17187